



Click [here](#) for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.15mm |
| W | 0.8mm +/-0.15mm |
| T | 0.8mm +/-0.07mm |
| S | 0.7mm MIN |
| B | 0.35mm +/-0.15mm |

| Packaging Specifications | |
|--------------------------|------------------------|
| Packaging | T&R, 330mm, Paper Tape |
| Packaging Quantity | 15000 |

| General Information | |
|---------------------|---|
| Series | SMD Comm X7R |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Class II |
| Features | Temperature Stable, Class II |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 4.8 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|---|
| Capacitance | 1000 pF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 20% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 48 Hours |
| Insulation Resistance | 100 GOhms |